

# DATA SHEET

**BFG403W**

**NPN 17 GHz wideband transistor**

Product specification  
Supersedes data of 1997 Oct 29

1998 Mar 11



# NPN 17 GHz wideband transistor

# BFG403W

## FEATURES

- Low current
- Very high power gain
- Low noise figure
- High transition frequency
- Very low feedback capacitance.

## APPLICATIONS

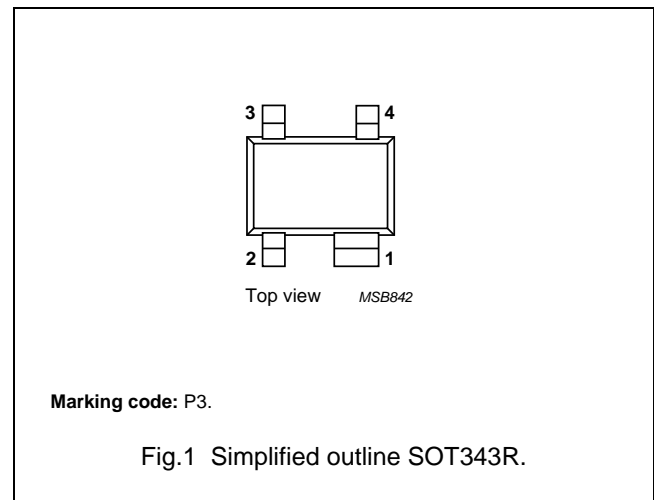
- Pager front ends
- RF front end
- Wideband applications, e.g. analog and digital cellular telephones, cordless telephones (PHS, DECT, etc.)
- Radar detectors.

## DESCRIPTION

NPN double polysilicon wideband transistor with buried layer for low voltage applications in a plastic, 4-pin dual-emitter SOT343R package.

## PINNING

PIN	DESCRIPTION
1	emitter
2	base
3	emitter
4	collector



## QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$V_{CBO}$	collector-base voltage	open emitter	–	–	10	V
$V_{CEO}$	collector-emitter voltage	open base	–	–	4.5	V
$I_C$	collector current (DC)		–	3	3.6	mA
$P_{tot}$	total power dissipation	$T_s \leq 140\text{ }^\circ\text{C}$	–	–	16	mW
$h_{FE}$	DC current gain	$I_C = 3\text{ mA}; V_{CE} = 2\text{ V}; T_j = 25\text{ }^\circ\text{C}$	50	80	120	
$C_{re}$	feedback capacitance	$I_C = 0; V_{CB} = 2\text{ V}; f = 1\text{ MHz}$	–	20	–	fF
$f_T$	transition frequency	$I_C = 3\text{ mA}; V_{CE} = 2\text{ V}; f = 2\text{ GHz}; T_{amb} = 25\text{ }^\circ\text{C}$	–	17	–	GHz
$G_{max}$	maximum power gain	$I_C = 3\text{ mA}; V_{CE} = 2\text{ V}; f = 2\text{ GHz}; T_{amb} = 25\text{ }^\circ\text{C}$	–	22	–	dB
F	noise figure	$I_C = 1\text{ mA}; V_{CE} = 2\text{ V}; f = 900\text{ MHz}; \Gamma_S = \Gamma_{opt}$	–	1	–	dB

## CAUTION

This product is supplied in anti-static packing to prevent damage caused by electrostatic discharge during transport and handling.

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**LIMITING VALUES**

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>CB0</sub>	collector-base voltage	open emitter	–	10	V
V <sub>CEO</sub>	collector-emitter voltage	open base	–	4.5	V
V <sub>EBO</sub>	emitter-base voltage	open collector	–	1	V
I <sub>C</sub>	collector current (DC)		–	3.6	mA
P <sub>tot</sub>	total power dissipation	T <sub>s</sub> ≤ 140 °C; note 1; see Fig.2	–	16	mW
T <sub>stg</sub>	storage temperature		–65	+150	°C
T <sub>j</sub>	operating junction temperature		–	150	°C

**Note**

1. T<sub>s</sub> is the temperature at the soldering point of the emitter pins.

**THERMAL CHARACTERISTICS**

SYMBOL	PARAMETER	VALUE	UNIT
R <sub>th j-s</sub>	thermal resistance from junction to soldering point	820	K/W

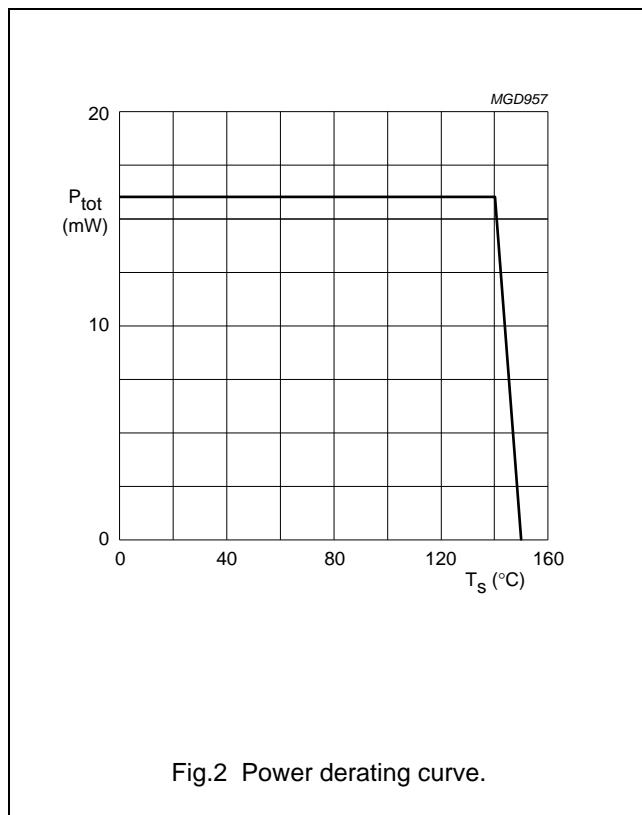


Fig.2 Power derating curve.

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## CHARACTERISTICS

$T_j = 25\text{ °C}$  unless otherwise specified.

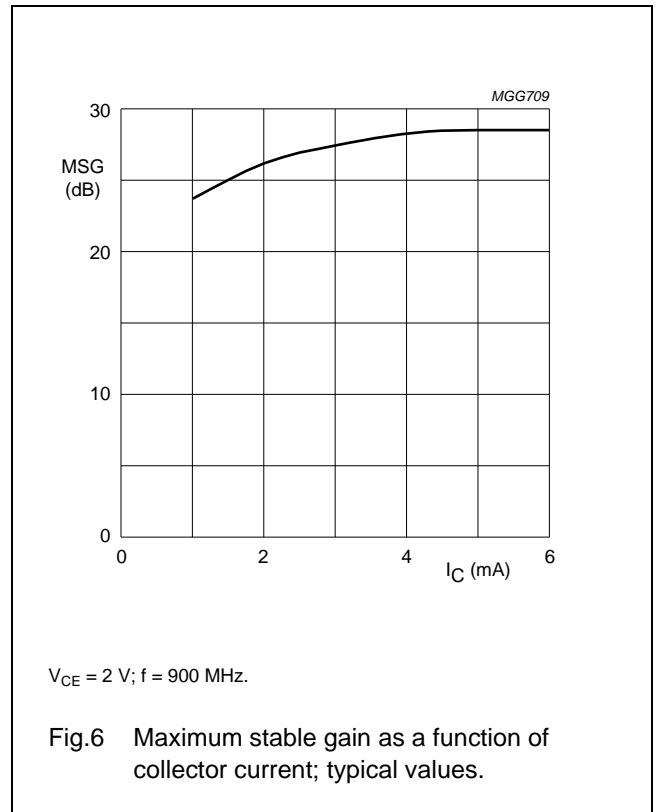
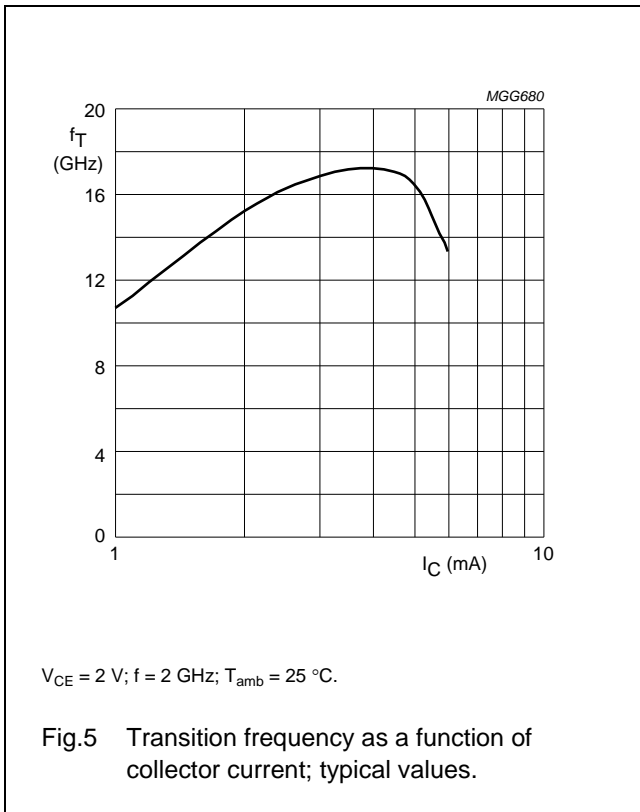
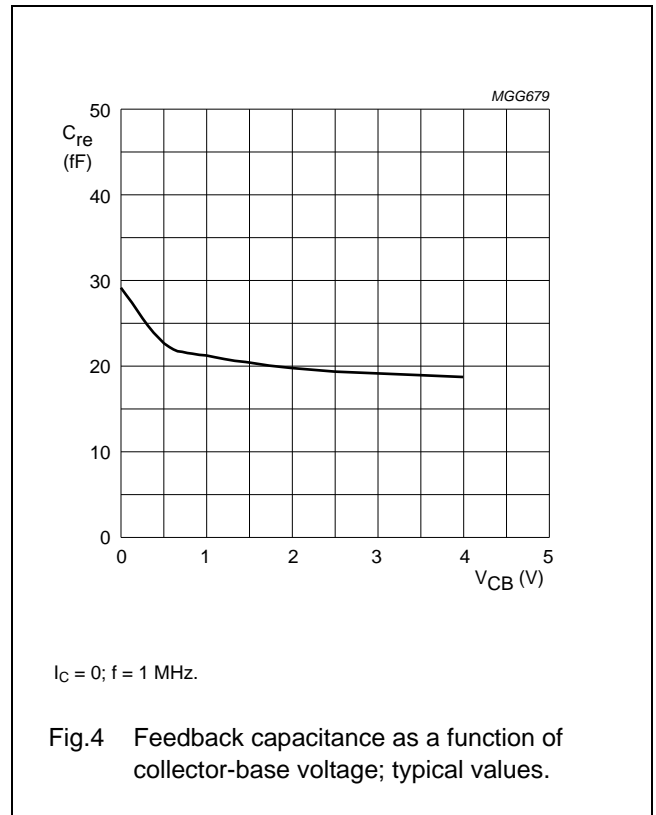
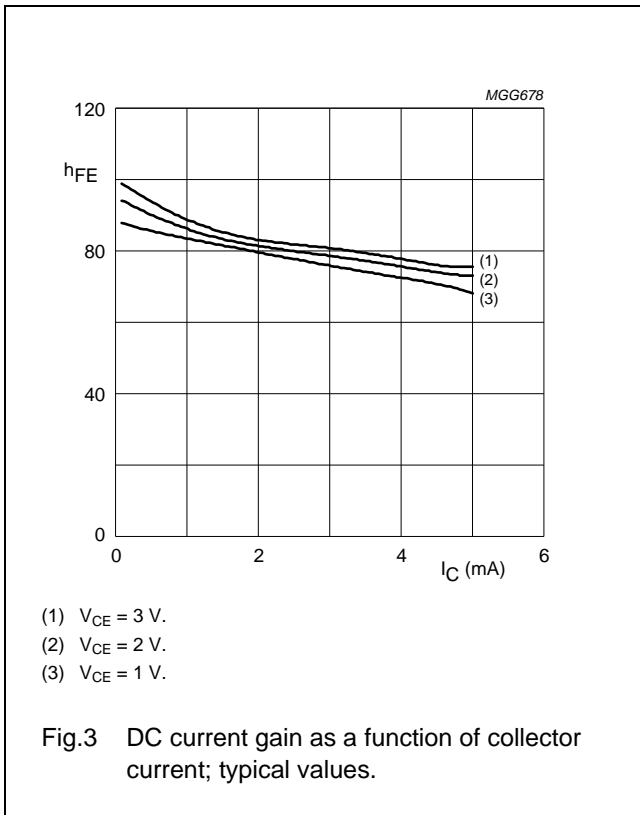
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$V_{(BR)CBO}$	collector-base breakdown voltage	$I_C = 2.5\ \mu\text{A}; I_E = 0$	10	–	–	V
$V_{(BR)CEO}$	collector-emitter breakdown voltage	$I_C = 1\ \text{mA}; I_B = 0$	4.5	–	–	V
$V_{(BR)EBO}$	emitter-base breakdown voltage	$I_E = 2.5\ \mu\text{A}; I_C = 0$	1	–	–	V
$I_{CBO}$	collector-base leakage current	$I_E = 0; V_{CB} = 4.5\ \text{V}$	–	–	15	nA
$h_{FE}$	DC current gain	$I_C = 3\ \text{mA}; V_{CE} = 2\ \text{V};$ see Fig.3	50	80	120	
$C_c$	collector capacitance	$I_E = i_e = 0; V_{CB} = 2\ \text{V}; f = 1\ \text{MHz}$	–	170	–	fF
$C_e$	emitter capacitance	$I_C = i_c = 0; V_{EB} = 0.5\ \text{V}; f = 1\ \text{MHz}$	–	315	–	fF
$C_{re}$	feedback capacitance	$I_C = 0; V_{CB} = 2\ \text{V}; f = 1\ \text{MHz};$ see Fig.4	–	20	–	fF
$f_T$	transition frequency	$I_C = 3\ \text{mA}; V_{CE} = 2\ \text{V}; f = 2\ \text{GHz};$ $T_{amb} = 25\text{ °C};$ see Fig.5	–	17	–	GHz
$G_{max}$	maximum power gain; note 1	$I_C = 0.5\ \text{mA}; V_{CE} = 1\ \text{V}; f = 900\ \text{MHz};$ $T_{amb} = 25\text{ °C};$ see Figs 6 and 8	–	20	–	dB
		$I_C = 3\ \text{mA}; V_{CE} = 2\ \text{V}; f = 2\ \text{GHz};$ $T_{amb} = 25\text{ °C};$ see Figs 7 and 8	–	22	–	dB
$ S_{21} ^2$	insertion power gain	$I_C = 0.5\ \text{mA}; V_{CE} = 1\ \text{V}; f = 900\ \text{MHz};$ $T_{amb} = 25\text{ °C};$ see Fig.8	–	5	–	dB
		$I_C = 3\ \text{mA}; V_{CE} = 2\ \text{V}; f = 2\ \text{GHz};$ $T_{amb} = 25\text{ °C};$ see Fig.8	–	14	–	dB
F	noise figure	$I_C = 1\ \text{mA}; V_{CE} = 2\ \text{V}; f = 900\ \text{MHz};$ $\Gamma_S = \Gamma_{opt};$ see Fig.13	–	1	–	dB
		$I_C = 1\ \text{mA}; V_{CE} = 2\ \text{V}; f = 2\ \text{GHz};$ $\Gamma_S = \Gamma_{opt};$ see Fig.13	–	1.6	–	dB
$P_{L1}$	output power at 1 dB gain compression	$I_C = 1\ \text{mA}; V_{CE} = 1\ \text{V}; f = 900\ \text{MHz};$ $Z_S = Z_{S\ opt}; Z_L = Z_{L\ opt};$ note 2	–	–5	–	dBm
ITO	third order intercept point	$I_C = 1\ \text{mA}; V_{CE} = 1\ \text{V}; f = 900\ \text{MHz};$ $Z_S = Z_{S\ opt}; Z_L = Z_{L\ opt};$ note 2	–	6	–	dBm

## Notes

- $G_{max}$  is the maximum power gain, if  $K > 1$ . If  $K < 1$  then  $G_{max} = \text{MSG}$ ; see Figs 6, 7 and 8.
- $Z_S$  is optimized for noise;  $Z_L$  is optimized for gain.

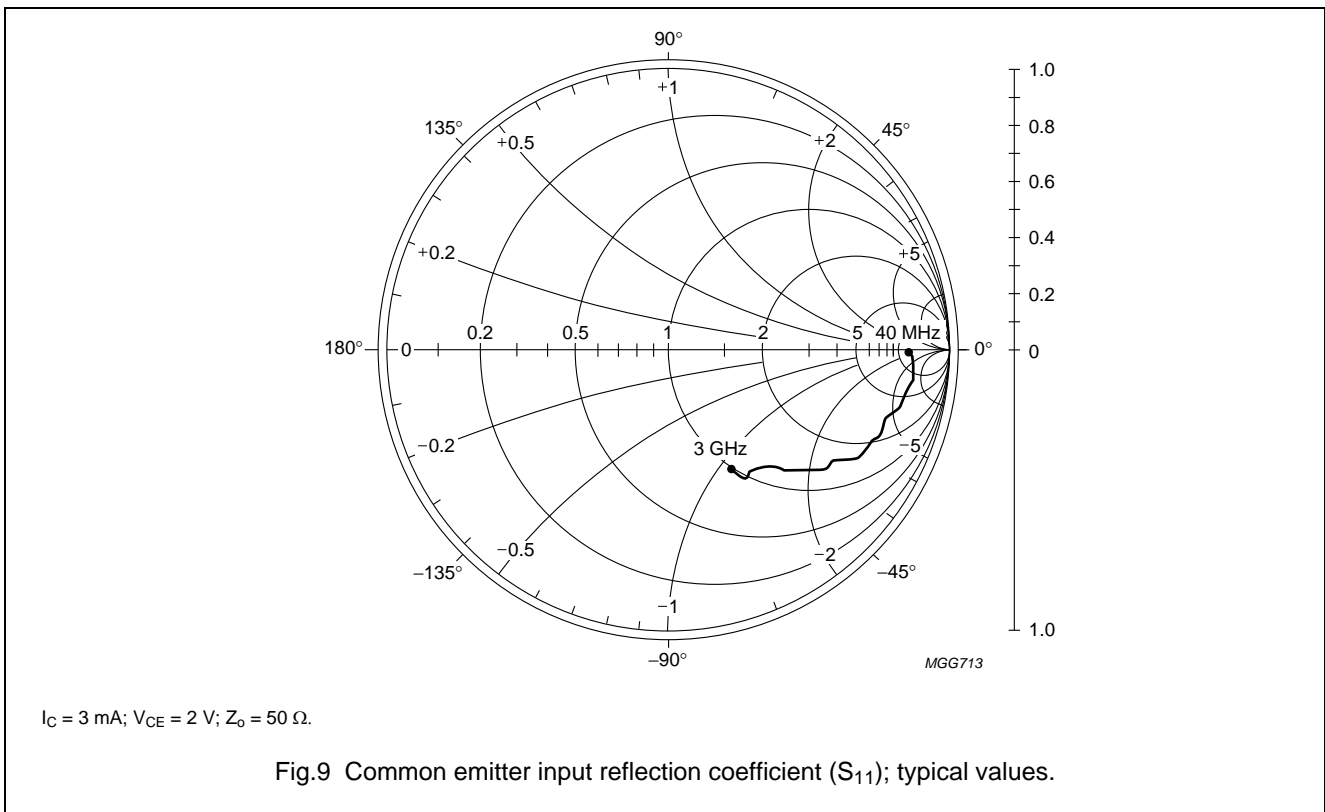
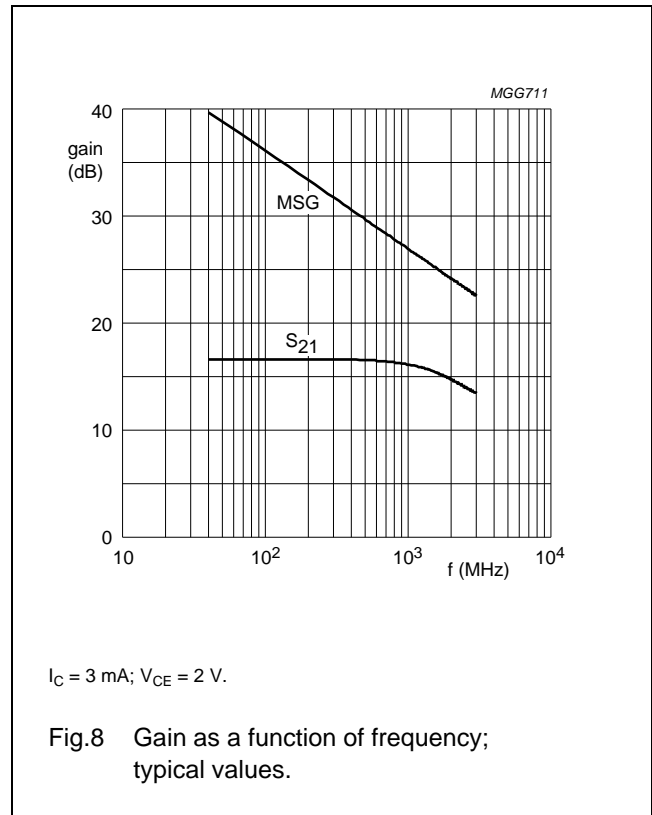
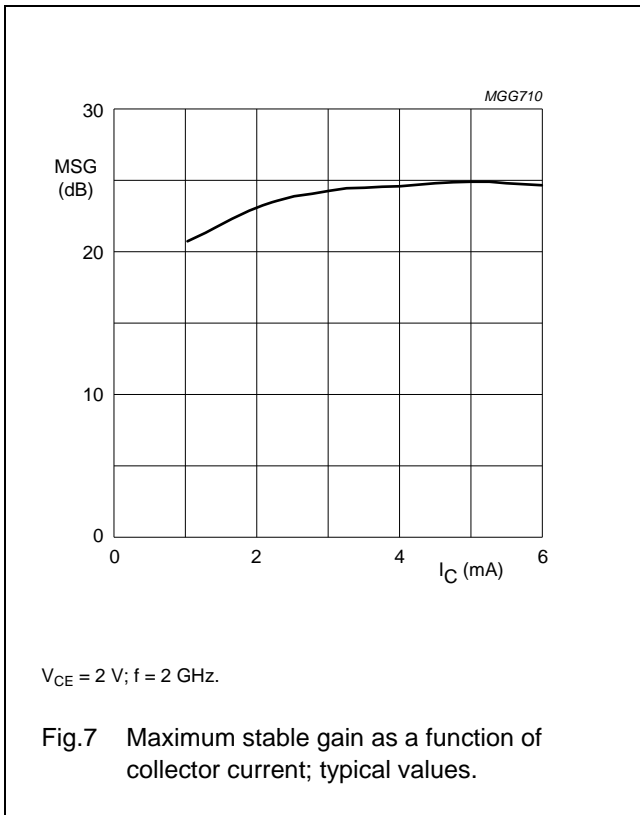
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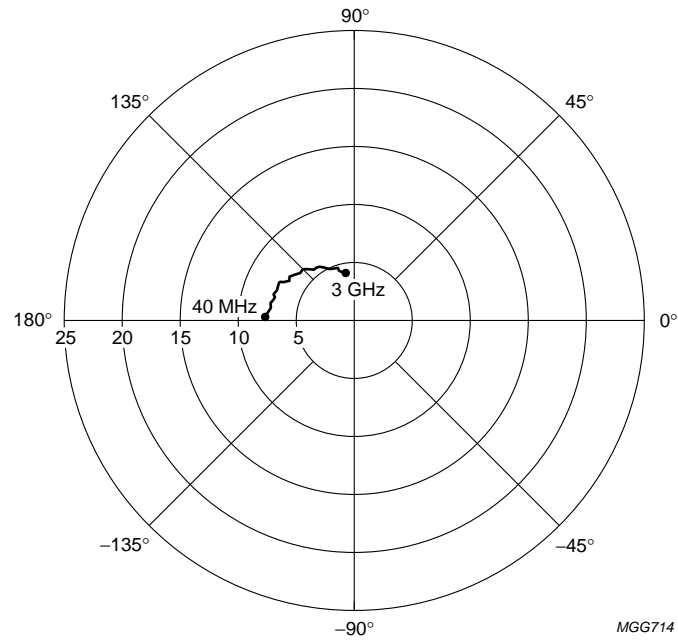
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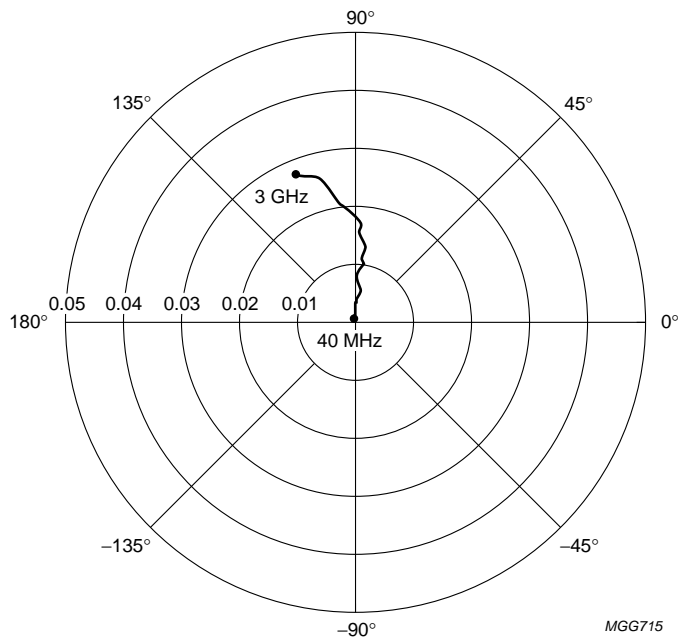
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$I_C = 3 \text{ mA}; V_{CE} = 2 \text{ V}.$

MGG714

Fig.10 Common emitter forward transmission coefficient ( $S_{21}$ ); typical values.



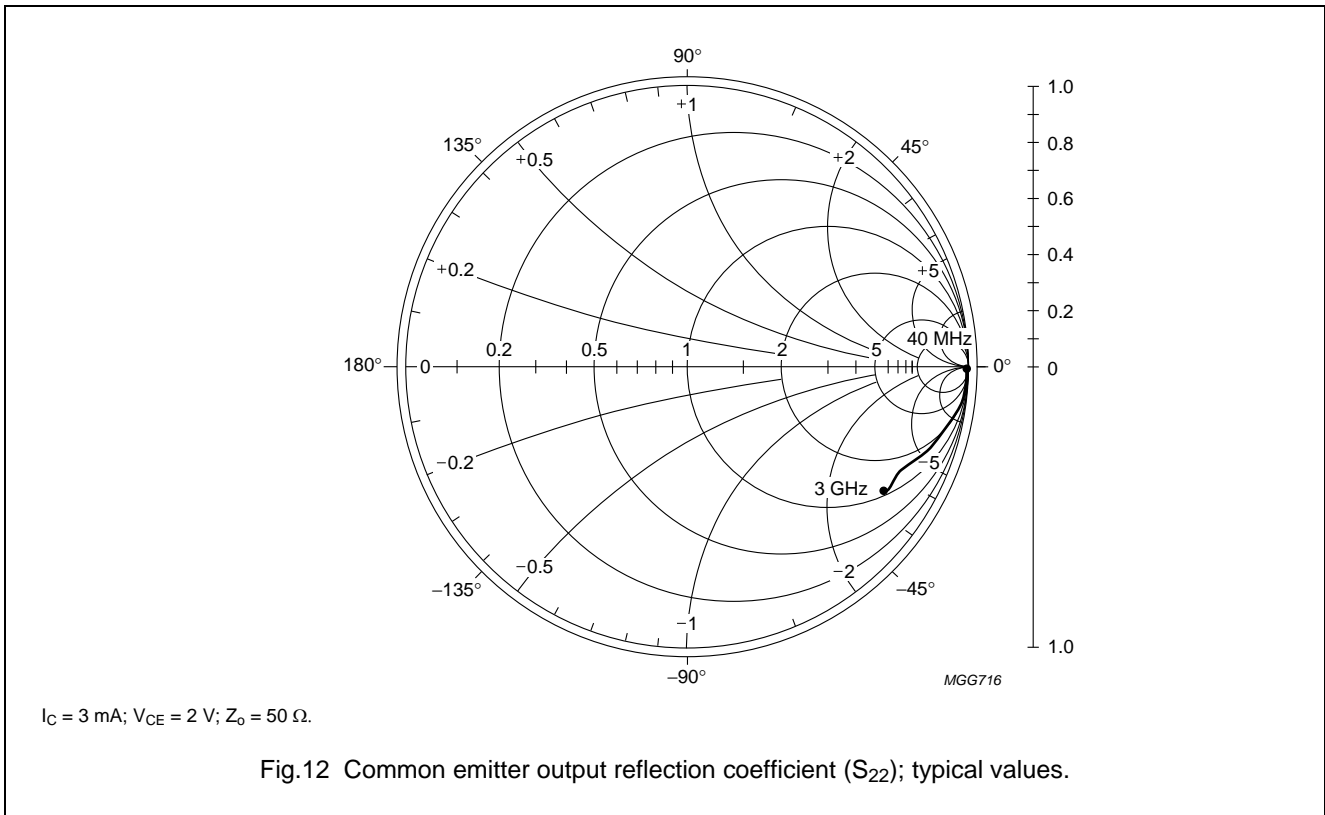
$I_C = 3 \text{ mA}; V_{CE} = 2 \text{ V}.$

MGG715

Fig.11 Common emitter reverse transmission coefficient ( $S_{12}$ ); typical values.

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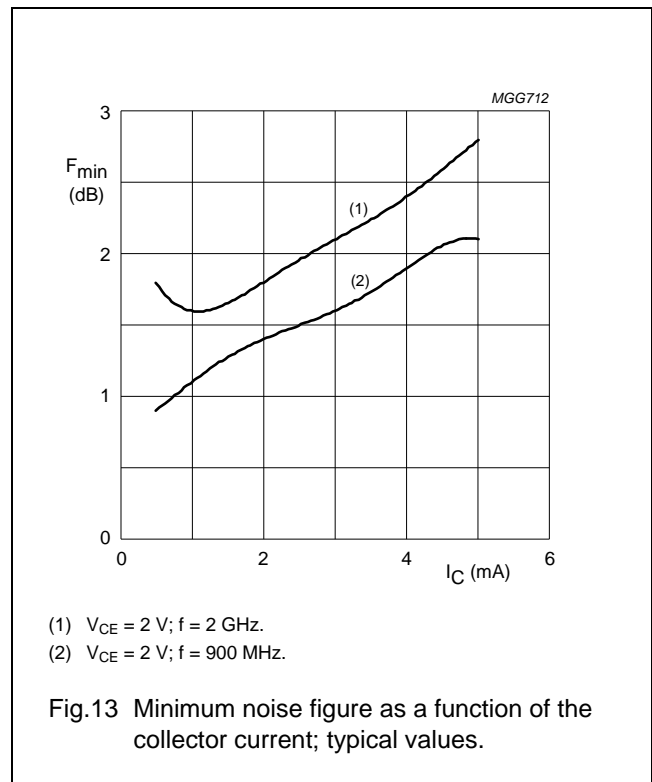
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Noise data

$V_{CE} = 2 \text{ V}$ ; typical values.

f (MHz)	$I_C$ (mA)	$F_{min}$ (dB)	$\Gamma_{mag}$	$\Gamma_{angle}$	$r_n$ ( $\Omega$ )
900	0.5	0.9	0.91	4.7	1.41
	1	1.1	0.83	5.1	1.12
	2	1.4	0.71	5.1	0.97
	3	1.6	0.62	5.0	0.88
	4	1.9	0.56	4.9	0.84
	5	2.1	0.50	4.2	0.82
2000	0.5	1.8	0.71	27.5	1.47
	1	1.6	0.74	26.1	1.11
	2	1.8	0.64	26.3	0.93
	3	2.1	0.56	26.1	0.91
	4	2.4	0.48	26.7	0.9
	5	2.8	0.45	25.8	0.85





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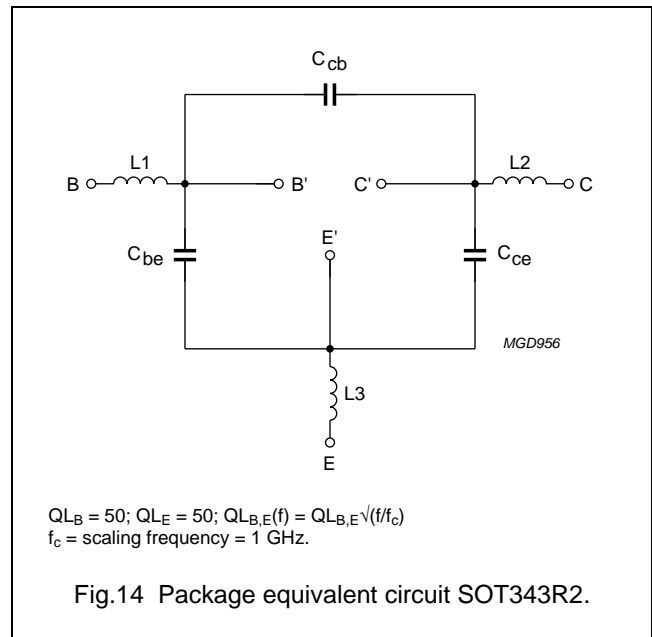
SPICE parameters for the BFG403W die

SEQUENCE No.	PARAMETER	VALUE	UNIT
1	IS	5.554	aA
2	BF	145.0	–
3	NF	0.993	–
4	VAF	31.12	V
5	IKF	35.75	mA
6	ISE	35.35	fA
7	NE	3.000	–
8	BR	11.37	–
9	NR	0.985	–
10	VAR	1.874	V
11	IKR	0.014	A
12	ISC	57.08	aA
13	NC	1.546	–
14	RB	122.4	$\Omega$
15	IRB	0.000	A
16	RBM	52.45	$\Omega$
17	RE	1.511	$\Omega$
18	RC	15.12	$\Omega$
19 (1)	XTB	1.500	–
20 (1)	EG	1.110	eV
21 (1)	XTI	3.000	–
22	CJE	36.61	fF
23	VJE	900.0	mV
24	MJE	0.346	–
25	TF	4.122	ps
26	XTF	68.20	–
27	VTF	2.004	V
28	ITF	0.179	A
29	PTF	0.000	deg
30	CJC	16.21	fF
31	VJC	556.9	mV
32	MJC	0.207	–
33	XCJC	0.500	–
34 (1)	TR	00.00	ns
35 (1)	CJS	78.59	fF
36 (1)	VJS	418.3	mV
37 (1)	MJS	0.239	–
38	FC	0.550	–

SEQUENCE No.	PARAMETER	VALUE	UNIT
39 (2)(3)	$C_{bp}$	145	fF
40 (2)	$R_{sb1}$	25	$\Omega$
41 (3)	$R_{sb2}$	19	$\Omega$

Notes

1. These parameters have not been extracted, the default values are shown.
2. Bonding pad capacity  $C_{bp}$  in series with substrate resistance  $R_{sb1}$  between B' and E'.
3. Bonding pad capacity  $C_{bp}$  in series with substrate resistance  $R_{sb2}$  between C' and E'.



List of components (see Fig.14)

DESIGNATION	VALUE	UNIT
$C_{be}$	80	fF
$C_{cb}$	2	fF
$C_{ce}$	80	fF
L1	1.1	nH
L2	1.1	nH
L3 (note 1)	0.25	nH

Note

1. External emitter inductance to be added separately due to the influence of the printed-circuit board.

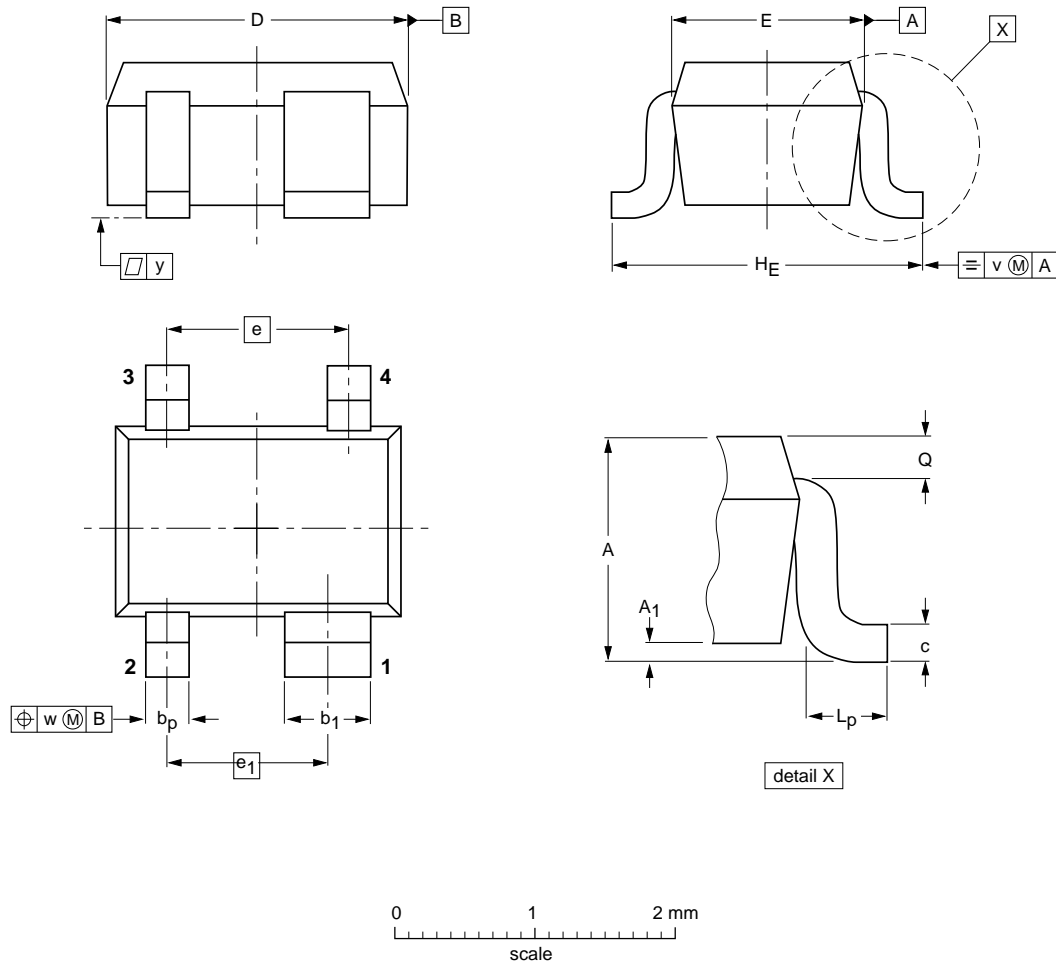
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PACKAGE OUTLINE

Plastic surface-mounted package; reverse pinning; 4 leads

SOT343R



DIMENSIONS (mm are the original dimensions)

UNIT	A	A <sub>1</sub> max	b <sub>p</sub>	b <sub>1</sub>	c	D	E	e	e <sub>1</sub>	H <sub>E</sub>	L <sub>p</sub>	Q	v	w	y
mm	1.1 0.8	0.1	0.4 0.3	0.7 0.5	0.25 0.10	2.2 1.8	1.35 1.15	1.3	1.15	2.2 2.0	0.45 0.15	0.23 0.13	0.2	0.2	0.1

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT343R						97-05-21 06-03-16

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## DATA SHEET STATUS

DOCUMENT STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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## **Contact information**

For additional information please visit: <http://www.nxp.com>

For sales offices addresses send e-mail to: [salesaddresses@nxp.com](mailto:salesaddresses@nxp.com)

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